

Customer No.: 31561
Docket No.: 11053-US-PA-1
Application No.: 10/707,457

REMARKS

Present Status of the Application

Claims 11-20 are pending at the current stage and the claim 11 was amended to better clarify the claimed subject matter of the present invention without introducing any new matter. For at least the foregoing reasons, applicants respectfully submit that the amended claims 11-20 patently define over prior art of record and reconsideration of this application is respectfully requested.

Discussion of amendment made to the claim 11

From paragraph [0043] in the specification, there discloses "FIG 10 is a cross-sectional view illustrating the formation of one metal bump, 1022 and 1062 respectively, on each of the two opposite surfaces of a diode 1012 with a planar P/N junction after physically separated into one individual die. " Accordingly, to better clarify the subject matter of the claim 11, a limitation of "wherein said at least one electrical contact areas are disposed on the two opposite surfaces of said circuit die," has been added.

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Discussion for rejection to claims under 35 U. S. C. 102(e)

1. Claims 11, 14-16 and 19-20 are rejected under 35 U. S. C. 102(e) as being anticipated by Williams (US publication no. 2004/0110118, hereinafter referred to Williams). Williams disclose a semiconductor device (Fig.8a) that contains a circuit die, said circuit die having at least one electrical contact area (421/422) for connection to the packaging of said semiconductor circuit, the electrical contact area being bond to the corresponding lead of said packaging by metallic material formed by a metal ball (423) of prescribed feed melted, wherein the metal ball contains alumina, tin, or lead and there are more than one metal ball

In response thereto, applicant respectfully traverses the objection based on the following arguments and thus withdrawal of objections to the claims 11, 14-16 and 19-20 is respectfully requested. First of all, to establish a prima facie case of anticipation, the prior art reference (i.e. Williams) should disclose all limitations of the amended independent claim 11. Additionally, throughout the disclosure of Williams, no circuit die with at least one electrical contact areas disposed on the two opposite surfaces thereof, can be found. In other words, Williams fails to teach, suggest or disclose "said at least one electrical contact areas are disposed on the two opposite surfaces of said circuit die," as claimed in the amended independent claim 11.

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Accordingly, the amended independent claim 11 in the present invention is not anticipated by Williams and thus patentable under 35 U. S.C. 102(e).

With respect to dependent claims 14-16 and 19-20, those claims are patentable in view of Williams as a matter of law for at least the following reason they contain all limitations of their patentable base independent claim 11.

Discussion for objection to claims under 35 U. S. C. 103(a)

2. Claims 12-13 and 17-18 are rejected under 35 U.S.C. 103(a) as being unpatentable over Williams in view of Lin (U.S. Patent No. 5,938,952).

In response thereto, applicants respectfully traverse the objection based on the following arguments and thus withdrawal of objections to the claims 12-13 and 17-18 is respectfully requested. As claims 12-13 and 17-18 are dependent claim, no matter whether they are conventional, they should be patentable over Williams in view of Lin as a matter of law for at least the reason that they contain all limitations of their patentable base independent claim 11.

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CONCLUSION

For at least the foregoing reasons, it is believed that all the pending claims 11-20 of the present application patently define over the prior art and are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted,

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